

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20070065635"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 12:45
S2	4772	428/458.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 12:49
S3	3535	roughness and adhesive adj3 strength	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 12:49
S4	51	S2 and S3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 12:49
S5	3662	roughness and (bonding bonded) adj3 strength	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 13:26
S6	3023	(surface adj3 roughness "R.sub.a" "R.sub.z") and (bonding bonded) adj3 strength	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 13:27
S7	35	S2 and S6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 13:28
S8	287	(surface adj3 roughness "R.sub.a" "R.sub.z") and S2	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 13:54
S9	201811	(palladium pd) and (ni nickel)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 13:54
S10	41	S8 and S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 13:54

S11	1	S10 and (palladium pd) near seed	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 13:54
S12	21	("4008343" "4325992" "4726006" "4775557" "4941940" "4959121").PN. OR ("5180639"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/06 14:07
S13	50	(surface adj3 roughness "R.sub.a" "R.sub.z") and chrome and palladium adj3 chloride	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 14:13
S14	168	printed adj3 circuit adj3 board same blasting	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:25
S15	5	printed adj3 circuit adj3 board same silicon adj3 carbide near (particles particulate nanoparticles microparticles)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:49
S16	698	printed adj3 circuit adj3 board same (silicon adj3 carbide diamond)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:50
S17	2	printed adj3 circuit adj3 board same (silicon adj3 carbide diamond) near (\$7particle \$7particulate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:51
S18	2	printed adj3 circuit adj3 board same (silicon adj3 carbide OR diamond OR tetraboron) near (\$7particle \$7particulate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:51
S19	9	printed adj3 circuit adj3 board.ab. and (silicon adj3 carbide OR diamond OR tetraboron) near (\$7particle \$7particulate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:52
S20	211	printed adj3 circuit adj3 board.ab. and (copper nickel) same (silicon adj3 carbide OR diamond OR tetraboron)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:53
S21	2	printed adj3 circuit adj3 board.ab. and (copper nickel) near trace same (silicon adj3 carbide OR diamond OR tetraboron)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:53
S22	63	printed adj3 circuit adj3 board same (copper nickel) same (silicon adj3 carbide OR tetraboron)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:56

S23	135	connector same (copper nickel) same (silicon adj3 carbide OR tetraboron)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:59
S24	7	connector same (copper nickel) same (silicon adj3 carbide OR tetraboron) same hardness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 15:59
S25	0	printed adj3 circuit adj3 board same (molybdenum adj3 disulfide) near (\$5particle \$5particulate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:01
S26	0	printed adj3 circuit adj3 board and (molybdenum adj3 disulfide) near (\$5particle \$5particulate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:02
S27	244	printed adj3 circuit adj3 board and (molybdenum adj3 disulfide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:02
S28	16	printed adj3 circuit adj3 board same (molybdenum adj3 disulfide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:02
S29	1112	electrical adj3 connector same (particulate particle nanoparticle microparticle)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:03
S30	1	electrical adj3 connector same (particulate particle nanoparticle microparticle) same (molybdenum adj3 disulfide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:03
S31	39	electrical adj3 connector same (particulate particle nanoparticle microparticle) same (lubricant friction)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:04
S32	0	molybdenum adj3 disulfide near embedded near (copper nickel gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:07
S33	263	molybdenum adj3 disulfide near (copper nickel gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:07
S34	124	molybdenum adj3 disulfide near (copper nickel gold) and (electrical circuit connector)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:08

S35	392	printed adj3 circuit adj3 board and embedded near (\$5particulate \$5particle \$5particulates \$5particles lubricant)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:14
S36	13	printed adj3 circuit adj3 board and embedded near (\$5particulate \$5particle \$5particulates \$5particles lubricant) same trace	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:15
S37	84	printed adj3 circuit adj3 board and embedded near (\$5particulate \$5particle \$5particulates \$5particles lubricant) same contact	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:15
S38	4	printed adj3 circuit adj3 board.ab. and (silicon adj3 carbide OR tetraboron) near abrasive	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/06 16:18
S39	1489	(blasted blasting) and palladium and (copper nickel) and (polymeric polymer polypropylene polyethylene polyurethane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 08:51
S40	718	(blasted blasting) and palladium and (copper nickel) and (polymeric polymer polypropylene polyethylene polyurethane) and (molybdenum disulfide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 08:51
S41	28	(blasted blasting) and palladium and (copper nickel) and (polymeric polymer polypropylene polyethylene polyurethane) and (molybdenum adj3 disulfide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 08:51
S42	314	(blasted blasting) and palladium and (copper nickel) and (polymeric polymer polypropylene polyethylene polyurethane) and surface adj3 roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 08:53
S43	5	(blasted blasting) and palladium near seed and (copper nickel) and (polymeric polymer polypropylene polyethylene polyurethane) and surface adj3 roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 08:53
S44	14	palladium near seed and (copper nickel) and (polymeric polymer polypropylene polyethylene polyurethane) and surface adj3 roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 08:55
S45	9	molybdenum adj3 disulfide near (particles nanoparticles microparticles particulate).ti.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 08:57
S46	11	molybdenum adj3 disulfide near (particles nanoparticles microparticles particulate) and (PCB circuit adj3 board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 08:58

S47	194	molybdenum adj3 disulfide near (particles nanoparticles microparticles particulate) and bearing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:03
S48	23	molybdenum adj3 disulfide near (particles nanoparticles microparticles particulate) and bearing and (polymeric polymer polypropylene polyethylene polyurethane) and surface adj3 roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:03
S49	15	palladium near seed and surface adj3 roughness and (aluminum titanium)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:06
S50	265	electroless\$5 and palladium and (molybdenum adj3 disulfide molybdenum adj3 sulfide tin adj3 sulfide cubic adj3 boron)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:19
S51	34	electroless\$5.ab. and palladium and (molybdenum adj3 disulfide molybdenum adj3 sulfide tin adj3 sulfide cubic adj3 boron)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:19
S52	9	electroless\$5 and palladium and (molybdenum adj3 disulfide molybdenum adj3 sulfide tin adj3 sulfide cubic adj3 boron) near (\$5particles \$5particulates \$5particulate \$5particle)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:28
S53	10	electroless adj3 plating same (molybdenum adj3 disulfide molybdenum adj3 sulfide tin adj3 sulfide cubic adj3 boron) near (\$5particles \$5particulates \$5particulate \$5particle)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:34
S54	57056	electroless\$3 adj3 (depositing deposited plated plating deposition)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:36
S55	24103	electroless\$3 adj3 (depositing deposited plated plating deposition). ti,ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:36
S56	435	palladium near (activate seed)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:37
S57	2122	palladium near (active activate seed)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:38

S58	26312	palladium same (active activate seed)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:38
S59	986	S55 and S58	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:38
S60	438	S59 and (\$6particles \$6particulates \$6particle \$6paticulate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:40
S61	13	S59 and (\$6particles \$6particulates \$6particle \$6paticulate) same (molybdenum adj3 \$2sulfide tin adj3 sulfide boron adj3 nitride "B. sub.4N" "MoS.sub.2" TiS PTFE polytetrafluoroethylene)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:42
S62	2	"20020192363"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:55
S63	250	S55 and (\$6particles \$6particulates \$6particle \$6paticulate) same (molybdenum adj3 \$2sulfide tin adj3 sulfide boron adj3 nitride "B. sub.4N" "MoS.sub.2" TiS PTFE polytetrafluoroethylene)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:58
S64	163	S55 and (\$6particles \$6particulates \$6particle \$6paticulate) same (molybdenum adj3 \$2sulfide tin adj3 sulfide boron adj3 nitride "B. sub.4N" "MoS.sub.2" TiS PTFE polytetrafluoroethylene).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:58
S65	3	S55 and (\$6particles \$6particulates \$6particle \$6paticulate) same (molybdenum adj3 \$2sulfide tin adj3 sulfide boron adj3 nitride "B. sub.4N" "MoS.sub.2" TiS PTFE polytetrafluoroethylene).ab. and substrate same (polymer polyamide polyethylene polypropylene polyurethane polymeric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 09:59
S66	44	S55 and (\$6particles \$6particulates \$6particle \$6paticulate) same (molybdenum adj3 \$2sulfide tin adj3 sulfide boron adj3 nitride "B. sub.4N" "MoS.sub.2" TiS PTFE polytetrafluoroethylene).ab. and (polymer polyamide polyethylene polypropylene polyurethane polymeric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 10:00

S67	132	S55 same (\$6particles \$6particulates \$6particle \$6paticulate) same (molybdenum adj3 \$2sulfide tin adj3 sulfide boron adj3 nitride "B.sub.4N" "MoS.sub.2" TiS PTFE polytetrafluoroethylene). ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 10:11
S68	135	S55 same (\$6particles \$6particulates \$6particle \$6paticulate) same (molybdenum adj3 \$2sulfide tin adj3 sulfide boron adj3 nitride "B.sub.4N" "MoS.sub.2" TiS PTFE polytetrafluoroethylene)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 10:12
S69	8	printed adj3 circuit adj3 board and trace same aluminum adj3 coating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 10:58
S70	0	printed adj3 circuit adj3 board and trace same (hart\$1coat kepla \$1coat)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:01
S71	0	printed adj3 circuit adj3 board and (hart\$1coat kepla\$1coat)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:02
S72	818	composite adj3 laminate and (copper nickel gold) and (aluminum titanium) same (aniodic\$5 ceramic \$5)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:04
S73	55	composite adj3 laminate.ab. and (copper nickel gold) and (aluminum titanium) same (aniodic\$5 ceramic \$5)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:04
S74	96	ceramic\$5 adj3 oxide near (aluminum alumina titanium titania) same black	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:07
S75	0	ceramic\$5 near black near ion	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:10
S76	5	foreign adj3 ion adj3 embedment	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:11
S77	2	"5035781".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:12

S78	4773	428/458.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:14
S79	1250	428/626.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:37
S80	463204	substrate same (polyamide polymeric polymer plastic ABS thermoplastic polyethylene polypropylene)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:38
S81	382	S79 and S80	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:38
S82	55	S79 and S80 and surface adj3 roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:39
S83	115	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:40
S84	107	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:41
S85	1	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold) and (palladium near (seed activate active))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:41
S86	1	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold) and (palladium near (seed activate active))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:41
S87	107	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:41
S88	0	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold) and ceramic near color\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:42
S89	33	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold) and ceramic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:42

S90	107	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:46
S91	40	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold) and electroless	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:46
S92	29	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold) and electroless and (aluminum titanium)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 11:48
S93	2	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold) and electroless and (aluminum titanium) same anodized	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:01
S94	5	S79 and S80 and (faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold) and electroless and (aluminum titanium) same oxid \$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:05
S95	2097	428/626-627.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:42
S96	484	S80 and S95	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:42
S97	179760	(faucet handle fixture decorat\$5 ornament\$5) and (nickel copper gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:42
S98	144	S96 and S97	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:43
S99	12	S98 and (aluminum titanium) near4 (oxidation oxidize anode anodoic\$5)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:44
S100	2	S98 and ceramic near (protective protection overcoat hardcoat resistant resistance)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 12:48
S101	2097	428/626-627.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:00

S102	936160	(ornament\$5 decorat\$5)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:00
S103	235	S101 and S102	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:01
S104	8095969	nickel gold copper ni au cu	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:02
S105	213	S103 and S104	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:02
S106	75	S105 and anod\$8	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:03
S107	6076342	(plastic polymer polymeric ABS polyamide polyimide polyethylene polypropylene plastic thermoplastic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:04
S108	51	S106 and S107	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:05
S109	10	color near ceramic near coating.ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:10
S110	0	color%4 near ceramic near (hard wear resistant resistance)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:11
S111	16	color\$4 near ceramic near (hard wear resistant resistance)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:11
S112	7	("3481840").URPN.	USPAT	OR	ON	2010/01/07 13:24
S113	3402	(palladium pd) near (activation seed activate active)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:25

S114	5	S101 and S113	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:25
S115	2	S101 and surface adj3 roughness near4 blasting	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:28
S116	8	adhesion adj3 improving and surface adj3 roughness near4 blasting	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:30
S117	12	adhesion adj3 improving same surface adj3 roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:34
S118	0	adhesion adj3 improving same "R. sub.a"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:36
S119	25	adhesion adj3 improving same roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:37
S120	1	adhesion near roughness near increased	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:39
S121	75	adhesion near roughness.ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 13:39
S122	3	"4231982".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 17:22
S123	2	"20030031803".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 17:30
S124	4	"3617363".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 17:31
S125	2	"6088947".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/07 17:31

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